

WHAT IS CLAIMED IS:

1. A semiconductor device, comprising:

a solid state device;

a semiconductor chip having a functional surface on which a functional element is formed, the semiconductor chip being bonded on a surface of the solid state device with the functional surface thereof facing the surface of the solid state device while maintaining a predetermined distance between the functional surface thereof and the surface of the solid state device;

an insulating film provided on the surface of the solid state device facing the semiconductor chip, the insulating film having an opening greater in size than the semiconductor chip when the surface of the solid state device facing the semiconductor chip is vertically viewed down in plane; and

a sealing layer that seals a space between the solid state device and the semiconductor chip.

2. A semiconductor device according to Claim 1, wherein the sealing layer is provided in such a manner as to fill the opening with the sealing layer.